AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-61 (Canceled).

62. (Currently Amended) A nitride semiconductor light emitting device comprising;

a substrate,

a first nitride semiconductor layer having an impurity concentration <u>less than</u> within-1 x 10^{17} /cm³, said first nitride semiconductor layer being a single layer,

a second nitride semiconductor layer having an n-type electrode, said second nitride semiconductor layer being a single layer,

a third nitride semiconductor layer having an impurity concentration <u>less</u>

than within-1 X 10¹⁷/cm³, said third nitride semiconductor layer being a super lattice layer of InGaN layers and GaN layers, and

<u>a separate and distinct</u> an-active layer where electrons and holes are combined.

63. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer is made of GaN or AlGaN and said second nitride semiconductor layer includes Si as an n-type impurity.

64. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said first nitride semiconductor layer is made of GaN or AlGaN.

65. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer has an carrier concentration more than 3×10^{18} /cm³.

66. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer has a resistivity less than 8×10^{-3} ohm $^{\circ}$ cm.

67. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

further comprising a buffer layer between said substrate and said first nitride semiconductor layer.

68. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said first nitride semiconductor layer has a thickness within

NAKAMURA et al Appl. No. 09/463,643 June 30, 2005

a range of from 0.1 to 20 µm.

69. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer has a thickness within a range of from 0.1 to 20 $\mu m_{\text{\tiny J}}$

70. (Currently Amended) A nitride semiconductor light emitting device comprising:

a substrate,

a first nitride semiconductor layer having an impurity concentration

<u>less than within-1 X 10¹⁷/cm³</u>, said first nitride semiconductor layer being a single layer,

a second nitride semiconductor layer having an n-type electrode, said second nitride semiconductor layer being a single layer,

a third nitride semiconductor layer being a super lattice layer of GaN layers, and

a separate and distinct an-active layer where electrons and holes are combined.

71. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer is made of GaN or AlGaN and said second nitride semiconductor layer includes Si as an n-type impurity.

72. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said first nitride semiconductor layer is made of GaN or AlGaN

73. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer has an carrier concentration more than 3×10^{18} /cm³.

74. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer has a resistivity less than 8 \times 10⁻³ ohm \cdot cm.

75. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

further comprising a buffer layer between said substrate and said first nitride semiconductor layer.

76. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said first nitride semiconductor layer has a thickness within a range of from 0.1 to 20 μm ,

77. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer has a thickness within a range of from 0.1 to 20 μm .

78. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said third nitride semiconductor layer being a super lattice layer of undoped GaN layers and Si doped GaN layers.

79. (Previously Presented) The nitride semiconductor light emitting device according to claim 78;

wherein said Si doped GaN layers are doped with Si to 1x10¹⁹/cm³.

80. (Previously Presented) The nitride semiconductor light emitting device according to claim 78;

wherein said undoped GaN layers have a thickness of 75Å and Si doped GaN layers have a thickness of 25Å.

NAKAMURA et al Appl. No. 09/463,643 June 30, 2005

81. (Previously Presented) The nitride semiconductor light emitting device according to claim 78;

wherein said third nitride semiconductor layer has a thickness of 600Å.